




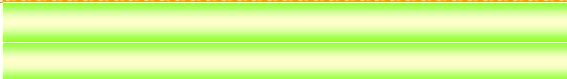








Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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12 189 FR4 35 L15.35 P06

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

12_189_FR4_35_L15.35_p06

Layers	in μ	Material	Build-Up	Assembly				
Layer-1	35 μ	Copper		} A1				
	60 μ	Prepreg						
	60 μ	Prepreg			} A2			
Layer-2	35 μ	Copper						
	150 μ	L-FR4				} A3		
Layer-3	35 μ	Copper						
	60 μ	Prepreg					} A4	
Layer-4	35 μ	Copper						
	60 μ	Prepreg						} A5
Layer-5	35 μ	Copper						
	60 μ	Prepreg						
Layer-6	35 μ	Copper						
	60 μ	Prepreg		} A7				
Layer-7	35 μ	Copper						
	60 μ	Prepreg			} A8			
Layer-8	35 μ	Copper						
	60 μ	Prepreg				} A9		
Layer-9	35 μ	Copper						
	60 μ	Prepreg					} A10	
Layer-10	35 μ	Copper						
	60 μ	Prepreg						} A11
Layer-11	35 μ	Copper						
	60 μ	Prepreg						
Layer-99	35 μ	Copper						

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